

Notification# 20200129003
Datasheet for ISOW7821
Information Only

The PCN is being reissued to correct the affected device list. The correction is highlighted in yellow below.

Date: February 04, 2020
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISOW7821DWE	null
ISOW7821FDWE	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200129003	PCN Date:	Feb 4, 2020
Title:	Datasheet for ISOW7821		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



ISOW7821

SLLSF40B – NOVEMBER 2017 – REVISED SEPTEMBER 2019

Changes from Revision A (March 2018) to Revision B	Page
• Made editorial and cosmetic changes throughout the document.....	1
• Added "Robust Isolation Barrier" bullet in Features	1
• Added ">100-Year Projected Lifetime at 1 kV _{RMS} Working Voltage" bullet in Features	1
• Added "Up to 5000 V _{RMS} Isolation Rating" bullet in Features	1
• Added "Up to 10 kV _{PK} Surge Capability" bullet in Features	1
• Added "±8 kV IEC 61000-4-2 Contact Discharge Protection across Isolation Barrier" bullet in Features	1
• Changed VDE standard name From: DIN V VDE V 0884-11:2017-01 To: DIN VDE V 0884-11:2017-01 in Features and Insulation Specifications table.....	1
• Added "EN 62368-1" standard in TUV certification bullet in Features	1
• Deleted "All Agency Certifications are Planned" bullet in Features	1
• Updated Simplified Schematic to show two isolation capacitors in series instead of a single capacitor for signal isolation channels.....	1
• Added "Contact discharge per IEC 61000-4-2; Isolation barrier withstand test" specification of ±8000 in ESD Ratings table.....	6
• Added table note "IEC ESD strike is applied across the barrier with all pins on each side tied together creating a two-terminal device" to ESD Ratings table.....	6
• Deleted "TJ or Junction temperature" parameter from Recommended Operating Conditions table as it is already specified in Absolute Maximum Ratings table.....	6
• Added "See Figure 34 " to TEST CONDITIONS of V _{IOWM} specification.....	8
• Updated Safety-Related Certifications table.....	9
• Added the following note to Figure 25 : "Optional 100 µF capacitor can be added between V _{CC} and GND1; refer to Power Supply Recommendations ".....	22
• Added the following note to Figure 30 : "Optional 100 µF capacitor can be added between V _{CC} and GND1; refer to Power Supply Recommendations ".....	28
• Added the following text to Design Requirements : "Optional 100 µF decoupling capacitor can be added between V _{CC} and GND1 pins; refer to Power Supply Recommendations for more details".....	29
• Added text to Power Supply Recommendations section to emphasise that input decoupling capacitor should be larger than output capacitor by at least 100 µF.....	31
• Added the following note to Figure 35 : "Optional 100 µF capacitor can be added between V _{CC} and GND1; refer to Power Supply Recommendations ".....	33

The datasheet number will be changing.

Device Family	Change From:	Change To:
ISOW7821	SLLSF40A	SLLSF40B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/ISOW7821>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
ISOW7821DWE	ISOW7821DWER	ISOW7821FDWE	ISOW7821FDWER

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.